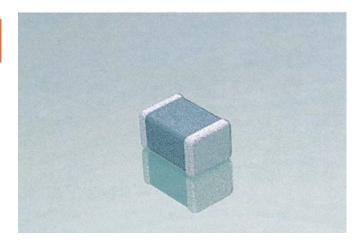
COG (NP0) Dielectric

General Specifications

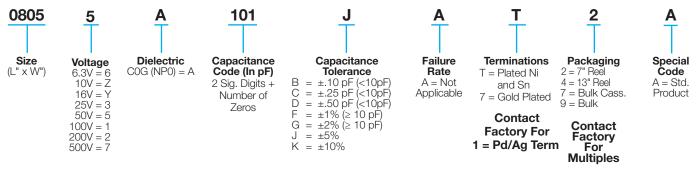




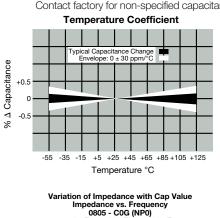
COG (NP0) is the most popular formulation of the "temperature-compensating," EIA Class I ceramic materials. Modern COG (NP0) formulations contain neodymium, samarium and other rare earth oxides.

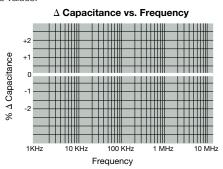
COG (NP0) ceramics offer one of the most stable capacitor dielectrics available. Capacitance change with temperature is 0 $\pm 30 \mathrm{ppm/^\circ C}$ which is less than $\pm 0.3\%$ $\Delta\mathrm{C}$ from -55°C to +125°C. Capacitance drift or hysteresis for COG (NP0) ceramics is negligible at less than $\pm 0.05\%$ versus up to $\pm 2\%$ for films. Typical capacitance change with life is less than $\pm 0.1\%$ for COG (NP0), one-fifth that shown by most other dielectrics. COG (NP0) formulations show no aging characteristics.

PART NUMBER (see page 2 for complete part number explanation)

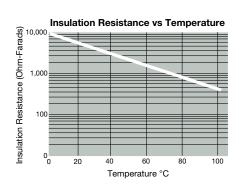


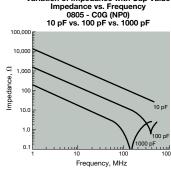
NOTE: Contact factory for availability of Termination and Tolerance Options for Specific Part Numbers. Contact factory for non-specified capacitance values.

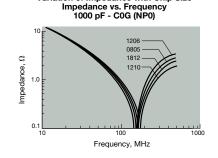


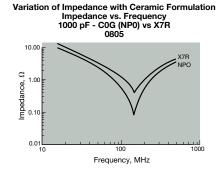


Variation of Impedance with Chip Size









C0G (NP0) Dielectric



Specifications and Test Methods

Parame	ter/Test	NP0 Specification Limits	Measuring Conditions							
	perature Range	-55°C to +125°C	Temperature Cycle Chamber							
Capac	itance	Within specified tolerance	Freq.: 1.0 MHz ± 10% for cap ≤ 1000 pF							
		<30 pF: Q≥ 400+20 x Cap Value	1.0 kHz ± 10% for cap > 1000 pF							
	d	≥30 pF: Q≥ 1000	Voltage: 1.0Vrms ± .2V							
Insulation	Pasistanas	100,000M Ω or 1000M Ω - μF,	Charge device with rated voltage for							
Insulation	nesistance	whichever is less	60 ± 5 secs @ room temp/humidity							
Dielectric	Strength	No breakdown or visual defects	Charge device with 300% of rated voltage for 1-5 seconds, w/charge and discharge current limited to 50 mA (max) Note: Charge device with 150% of rated voltage for 500V devices.							
	Appearance	No defects	Deflection							
Resistance to	Capacitance Variation	±5% or ±.5 pF, whichever is greater	Test Time: 30 seconds							
Flexure Stresses	Q	Meets Initial Values (As Above)	V							
	Insulation Resistance	≥ Initial Value x 0.3	90 mm							
Solde	rability	≥ 95% of each terminal should be covered with fresh solder	Dip device in eutectic for 5.0 ± 0.							
	Appearance	No defects, <25% leaching of either end terminal								
	Capacitance Variation	≤ ±2.5% or ±.25 pF, whichever is greater	Dip device in eutectic solder at 260°C for 60 seconds. Store at room temperature for 24 ± 2 hours before measuring electrical properties.							
Resistance to Solder Heat	Q	Meets Initial Values (As Above)								
	Insulation Resistance	Meets Initial Values (As Above)								
	Dielectric Strength	Meets Initial Values (As Above)								
	Appearance	No visual defects	Step 1: -55°C ± 2°	30 ± 3 minutes						
	Capacitance Variation	≤ ±2.5% or ±.25 pF, whichever is greater	Step 2: Room Temp	≤ 3 minutes						
Thermal Shock	Q	Meets Initial Values (As Above)	Step 3: +125°C ± 2°	30 ± 3 minutes						
SHOCK	Insulation Resistance	Meets Initial Values (As Above)	Step 4: Room Temp	≤ 3 minutes						
	Dielectric Strength	Meets Initial Values (As Above)	Repeat for 5 cycles and measure after 24 hours at room temperature							
	Appearance	No visual defects								
	Capacitance Variation	≤ ±3.0% or ± .3 pF, whichever is greater	Charge device with twice rated voltage in							
Load Life	Q (C=Nominal Cap)	≥ 30 pF: Q≥ 350 ≥10 pF, <30 pF: Q≥ 275 +5C/2 <10 pF: Q≥ 200 +10C	test chamber set for 1000 hou	ırs (+48, -0).						
	Insulation Resistance	≥ Initial Value x 0.3 (See Above)	Remove from test chamber and stabilize at room temperature for 24 hours							
	Dielectric Strength	Meets Initial Values (As Above)	before measuring.							
	Appearance	No visual defects								
	Capacitance Variation	≤ ±5.0% or ± .5 pF, whichever is greater	Store in a test chamber set at 85°C ± 2°C/85% ± 5% relative humidity for 1000 hours (+48, -0) with rated voltage applied. Remove from chamber and stabilize at room temperature for 24 ± 2 hours before measuring.							
Load Humidity	Q	≥ 30 pF: Q≥ 350 ≥10 pF, <30 pF: Q≥ 275 +5C/2 <10 pF: Q≥ 200 +10C								
	Insulation Resistance	≥ Initial Value x 0.3 (See Above)								
	Dielectric Strength	Meets Initial Values (As Above)								



C0G (NP0) Dielectric





PREFERRED SIZES ARE SHADED

					63						[
SIZE	01005	0201	0402		0603			0805		1206					
Soldering	Reflow Only	Reflow Only	Reflow/Wav	ve e	Reflow/Wave			Reflow/Wave	Reflow/Wave						
Packaging mm	All Paper 0.40 ± 0.02	All Paper 0.60 ± 0.03	All Paper 1.00 ± 0.10		All Paper 1,60 ± 0,15			aper/Embossed				mbossec	ı		
(L) Lerigiti (in.)	(0.016 ± 0.0008)	(0.024 ± 0.001)	(0.040 ± 0.00)	4)	(0.063 ± 0.006)			(0.079 ± 0.008)	3.20 ± 0.20 (0.126 ± 0.008)						
(W) Width mm (in.)	0.20 ± 0.02 (0.008 ± 0.0008)	0.30 ± 0.03 (0.011 ± 0.001)	0.50 ± 0.10 (0.020 ± 0.00	4)	0.81 ± 0.15 (0.032 ± 0.006)			1.25 ± 0.20 (0.049 ± 0.008)	1.60 ± 0.20 (0.063 ± 0.008)						
(t) Terminal mm (in.)	0.10 ± 0.04 (0.004 ± 0.016)	0.15 ± 0.05 (0.006 ± 0.002)	0.25 ± 0.15 (0.010 ± 0.00		0.35 ± 0.15 (0.014 ± 0.006)			0.50 ± 0.25 (0.020 ± 0.010)	0.50 ± 0.25 (0.020 ± 0.010)						
WVDC	16	25 50	16 25	50 16	25 50	100	16 25	50 100		16	25 50	100	200	500	
Cap 0.5 (pF) 1.0	В	A A		C G G	G G G G	G G	J J	J J	J	J	J J	J	J	J	
1.2 1.5	B B	A A		C G G	G G G	G G	JJ	JJJ	J	J	JJ	J	J	J J	
1.8	В	A A	C C	C G	G G	G	J J	J J	J	J	J J	J	J	J	
2.2 2.7	B B	A A	C C C	C G G	G G G G	G G	J J	JJJ	J	J	J J	J	J	J	
3.3 3.9	B B	A A	CCC	C G	G G	G G	JJ	JJ	J	J	J J	J	J	J	
4.7	В	A A	C C	C G	G G	G	J J	J J	J	J	J J	J	J	J	
5.6 6.8	B B	A A	C C C	C G	G G	G G	J J	JJJ	J	J	7 J	J	J	J	
8.2	B B	A A	C C	C G	G G	G G	J J	J J	J	J	J J	J	J	J	
12	В	A A	CC	C G	G G	G	J J	J J	J	J	J J	J	J	J	
15 18	B B	A A	C C	C G	G G	G G	J J	J J	J	J	J J	J	J	J	
22 27	В	A A	C C	C G G	G G	G G	J J	JJJ	J	J	JJ	J	J	J J	
33		A A	C C	C G	G G	G	J J	J J	J	J	J J	J	J	J	
39 47		A A		C G	G G G	G G	JJ	JJJ	J	J	JJ	J	J	J	
56 68		A A	C C	C G G	G G G G	G G	J J	J J	J	J	J J	J	J J	J	
82		А	C C	C G	G G	G	J J	J J	J	J	J J	J	J	J	
100 120		Α		C G G	G G G	G G	JJ	JJJ	J	J	JJ	J	J	J J	
150 180			C C	C G	G G	G G	J J	J J	J	J	J J	J	J	J	
220			C C	C G	G G	G	J J	J J	J	J	J J	J	J	M	
270 330			C C	C G	G G	G G	J J	J J	M	J	J J	J	J	M M	
390 470				C G G	G G		J J	JJ	M M	J	JJ	J	J	M M	
560				G	G G		J J	J J	M	J	J J	J	J	М	
680 820				G	G G G		JJ	JJJ		J	JJ	J	J M	Р	
1000 1200				G	G G		J J	J J		J J	J J	J	Q Q		
1500							J J	J		J	J J	М	Q		
1800 2200							JJ	J N		J	J M J M	M P			
2700 3300							J J	N		J	J M	P P			
3900							J J			J	J M	Р			
4700 5600	-						J J			J	J M	Р			
6800 8200		>								M M	M M				
Cap 0.010		<u></u>	~~~~~							M	M				
(µF) 0.012 0.015			7 /// }	,1											
0.018 0.022															
0.027		ľ	fil .												
0.033 0.039				1											
0.047										\vdash		+			
0.082															
0.1 WVDC	25	50 16	25 50	16 25	50 100	16	25 50	100 200	16	25	50 100	200	500		
SIZE	01005	0201	0402		0603		0805			1206					
Letter	A B	C		G J	K	M	N	P 1.50	Q 1.70	Х	Y	Z			
	0.22 .013) (0.009			.90 0.94 035) (0.03		1.27 (0.050		1.52 (0.060)	1.78 (0.070)	2.29 (0.090)	(0.100)	2.79))		
		PAPER	. , ,		. ,			EMBOSSED	(31113)						



C0G (NP0) Dielectric



Capacitance Range

PREFERRED SIZES ARE SHADED

FREF	PREFERRED SIZES ARE SHADED																				
SIZ	E	1210					1812					1825			2220			2225			
Solder	ring	Reflow Only					Reflow Only					Reflow Only			Reflow Only			Reflow Only			
Packa		Paper/Embossed 3.20 ± 0.20				All Embossed					All Embossed 4.50 ± 0.30			All Embossed			All Embossed 5.72 ± 0.25				
(L) Length	mm (in.)	(0.126 ± 0.008)				4.50 ± 0.30 (0.177 ± 0.012)					(0.177 ± 0.012)			5.70 ± 0.40 (0.225 ± 0.016)			(0.225 ± 0.010)				
(W) Width	mm (in.)	2.50 ± 0.20 (0.098 ± 0.008)				3.20 ± 0.20 (0.126 ± 0.008)					6.40 ± 0.40 (0.252 ± 0.016)			5.00 ± 0.40 (0.197 ± 0.016)			6.35 ± 0.25 (0.250 ± 0.010)				
(t) Terminal	mm (in.)	0.50 ± 0.25 (0.020 ± 0.010)					0.61 ± 0.36 (0.024 ± 0.014)					0.61 ± 0.36 (0.024 ± 0.014)			0.64 ± 0.39 (0.025 ± 0.015)			0.64 ± 0.39 (0.025 ± 0.015)			
	WVDC					25				50	100	200	50	100	200	50	100	200			
Cap (pF)	0.5 1.0																				
(DI)	1.2																				
	1.5 1.8															-	· •				
	2.2																5	· _	- W		
	2.7 3.3															<u> </u>		_		*	
	3.9																(~	$\overline{}$) ↓ T	
	4.7 5.6															-		4			
	6.8																	t			
	8.2 10					J										+			ĺ	I	
	12					J															
	15 18					J															
	22					J															
	27 33					J															
	39					J															
	47 56					J															
	68					J															
-	82 100					J															
	120					J															
	150 180					J															
	220 270					J															
	330					J															
	390 470					M M															
	560	J	J	J	J	M															
	680 820	J J	J	J	J	M M															
	1000	J	J	J	J	M	K	K	K	K	М	М	М	М				М	М	Р	
	1200 1500	J	J	J	M M	M M	K K	K K	K K	K K	M M	M M	M M	M M				M M	M M	P P	
	1800	J	J	J	М	141	K	K	K	K	М	М	М	М				М	М	Р	
	2200 2700	J	J	J	QQ		K K	K K	K K	K	P Q	M M	M M	M M				M M	M M	P P	
	3300	J	J	J			K	K	K	P	Q	М	М	М			Х	М	М	Р	
	3900 4700	J	J	M M			K K	K	K K	P P	Q Q	M M	M M	M M	Х	Х	X	M M	M M	P P	
	5600 6800	J	J				K K	K K	М	P X	Х	M M	M M	M M	X	X	X	М	М	P P	
	8200	J	J				K	М	M M			М	М	IVI	Х	Х	Х	M M	M M	Р	
Cap (µF)	0.010 0.012	J	J				K K	M M	М			M M	M M		X	X	X	M M	M M	P P	
(Fit)	0.015	- 0	3				М	М				М	М		Х	Х	Х	М	М	Υ	
	0.018 0.022						M M	M M				P P	М		X X	X	Х	M M	M Y	Y	
	0.027						М	М				Р			Х	Х	\sqcup	Р	Ϋ́	Ϋ́	
	0.033 0.039						M M	M M				P P			X Y	X		P P			
	0.047						М	М				P			Ϋ́			Р			
	0.068 0.082						M M	M M										P Q			
	0.1			100	000	500			100	000	500		100	000		400	000	Q	400	600	
	WVDC SIZE	25 50 100 200 500 1210			25	25 50 100 200 500 1812				50 100 200 1825			50 100 200 2220			50	100 2225	200			
Letter	A	C		E	G			K M N				•			X Y Z						
Max.	0.33	0.5	6	0.71	0.90	0.9	94	1.02	1.27	1.4	40	1.52	1.78	2.	29	2.54	2.79				
Thickness	(0.013)	(0.02		0.028)	(0.035)	(0.0)37)	37) (0.040) (0.050) (0.055) ((0.070)	(0.0)90)	(0.100)	(0.110)				
		PAPER EMBOSSED																			

